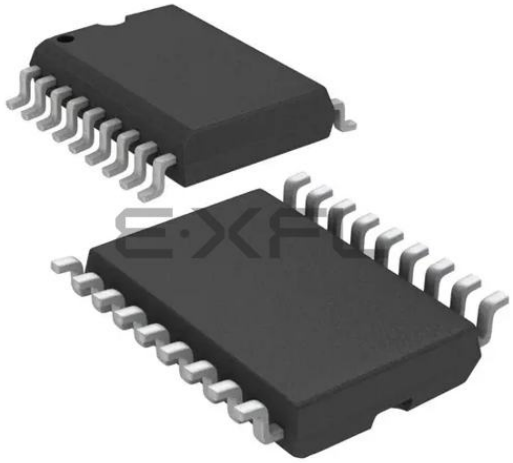
Microchip Technology - DSPIC33FJ32GP101T-E/SO Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32gp101t-e-so

NOTES:

TABLE 4-18: CTMU REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CTMUCON1	033A	CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	—	—	—	—	—	—	—	—	0000
CTMUCON2	033C	EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—	0000
CTMUICON	033E	ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-19: REAL-TIME CLOCK AND CALENDAR REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ALRMVAL	0620	Alarm Value Register Window based on ALRMPTR<1:0>																xxxx
ALCFGRPT	0622	ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0	ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0	0000
RTCVAL	0624	RTCC Value Register Window based on RTCPTR<1:0>																xxxx
RCFGCAL	0626	RTCEN	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	RTCPTR1	RTCPTR0	CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: PAD CONFIGURATION REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PADCFG1	02FC	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RTSECSEL	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-1: SR: CPU STATUS REGISTER(1)

R-0	R-0	R/C-0	R/C-0	R-0	R/C-0	R-0	R/W-0
OA	OB	SA	SB	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	**IPL1(2)**	**IPL0(2)**	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)
111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see Register 3-1.
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

REGISTER 7-2: CORCON: CORE CONTROL REGISTER(1)

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	**IPL3(2)**	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: For complete register details, see Register 3-2.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

REGISTER 7-25: IPC15: INTERRUPT PRIORITY CONTROL REGISTER 15

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	FLTA1IP2(1)	FLTA1IP1(1)	FLTA1IP0(1)	—	RTCIP2	RTCIP1	RTCIP0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **FLTA1IP<2:0>:** PWM1 Fault A Interrupt Priority bits(1)

111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **RTCIP<2:0>:** RTCC Interrupt Priority bits

111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-0 **Unimplemented:** Read as '0'

Note 1: These bits are available in dsPIC(16/32)MC10X devices only.

REGISTER 9-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1 (CONTINUED)

bit 3 **SPI1MD:** SPI1 Module Disable bit
1 = SPI1 module is disabled
0 = SPI1 module is enabled

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **AD1MD:** ADC1 Module Disable bit(2)
1 = ADC1 module is disabled
0 = ADC1 module is enabled

Note 1: These bits are available in dsPIC33FJ32(GP/MC)10X devices only.

2: PCFGx bits have no effect if the ADC module is disabled by setting this bit. When the bit is set, all port pins that have been multiplexed with ANx will be in Digital mode.

REGISTER 9-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	IC3MD	IC2MD	IC1MD
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	OC2MD	OC1MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10 **IC3MD:** Input Capture 3 Module Disable bit
1 = Input Capture 3 module is disabled
0 = Input Capture 3 module is enabled

bit 9 **IC2MD:** Input Capture 2 Module Disable bit
1 = Input Capture 2 module is disabled
0 = Input Capture 2 module is enabled

bit 8 **IC1MD:** Input Capture 1 Module Disable bit
1 = Input Capture 1 module is disabled
0 = Input Capture 1 module is enabled

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **OC2MD:** Output Compare 2 Module Disable bit
1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit
1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

10.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See **"Pin Diagrams"** for the available pins and their functionality.

10.2 Configuring Analog Port Pins

The AD1PCFGL and TRISx registers control the operation of the Analog-to-Digital port pins. The port pins that are to function as analog inputs must have their corresponding TRISx bit set (input). If the TRISx bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The AD1PCFGL register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

When the PORTx register is read, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

10.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP. A demonstration is shown in Example 10-1.

10.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States, even in Sleep mode, when the clocks are disabled. Depending on the device pin count, up to 21 external signals (CNx pin) can be selected (enabled) for generating an interrupt request on a Change-of-State.

Four control registers are associated with the CN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up connected to it. The pull-ups act as a current source connected to the pin and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-ups for the corresponding pins.

Note:	Pull-ups on Input Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0          ; Configure PORTB<15:8> as inputs
MOV   W0, TRISBB          ; and PORTB<7:0> as outputs
NOP                       ; Delay 1 cycle
btss  PORTB, #13          ; Next Instruction
```

REGISTER 10-7: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	OCFAR4	OCFAR3	OCFAR2	OCFAR1	OCFAR0
bit 7							bit 0

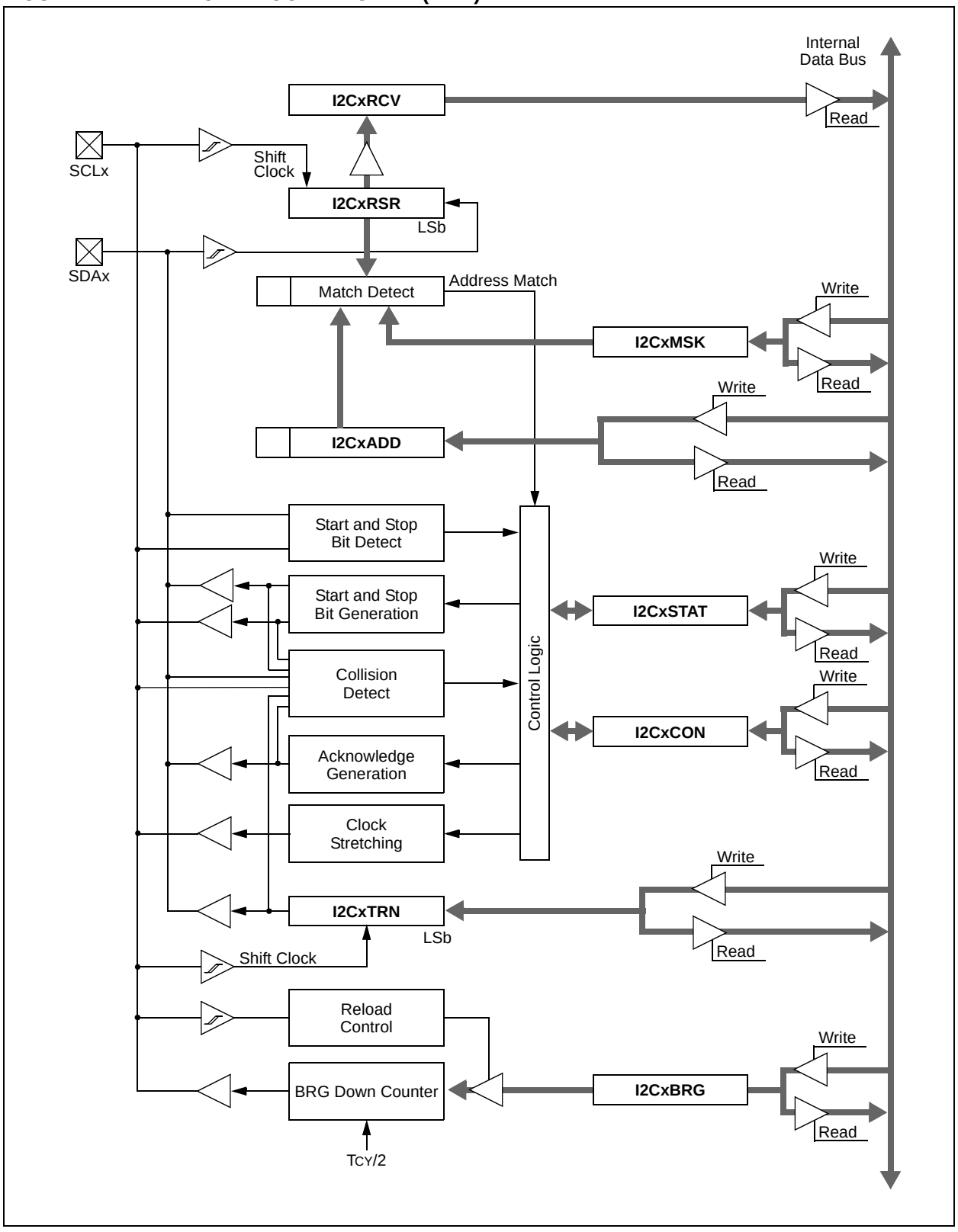
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **OCFAR<4:0>:** Assign Output Capture A (OCFA) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

FIGURE 17-1: I²C™ BLOCK DIAGRAM (x = 1)



18.3 UART Control Registers

REGISTER 18-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by the UEN<1:0> bits
- 0 = UARTx is disabled; all UARTx pins are controlled by port latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** UARTx Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits
- 11 = UxTX, UxRX and BCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLK pins are controlled by port latches

bit 7 **WAKE:** Wake-up on Start bit Detect During Sleep Mode Enable bit
- 1 = UARTx will continue to sample the UxRX pin; interrupt is generated on falling edge, bit is cleared in hardware on following rising edge
- 0 = No wake-up is enabled

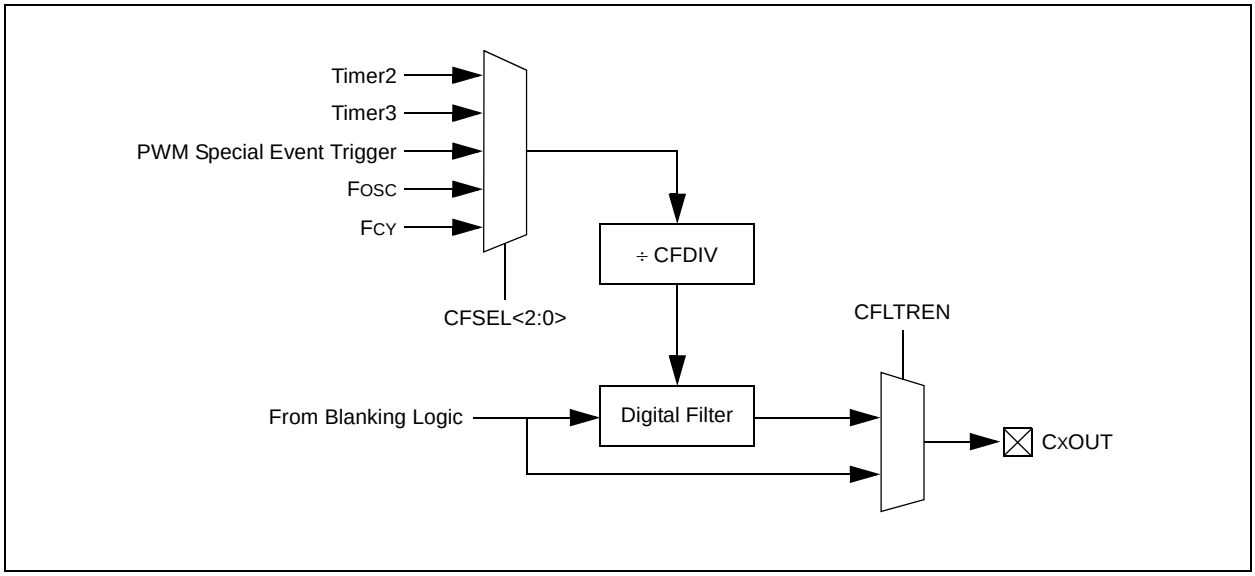
bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Enables Loopback mode
- 0 = Loopback mode is disabled

bit 5 **ABAUD:** Auto-Baud Enable bit
- 1 = Enables baud rate measurement on the next character – requires reception of a Sync field (55h) before other data; cleared in hardware upon completion
- 0 = Baud rate measurement is disabled or completed

Note 1: Refer to **"UART"** (DS70188) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is available for 16x BRG mode (BRGH = 0) only.

FIGURE 20-4: DIGITAL FILTER INTERCONNECT BLOCK DIAGRAM



REGISTER 20-2: CMxCON: COMPARATOR x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator x Enable bit
1 = Comparator x is enabled
0 = Comparator x is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator x output is inverted
0 = Comparator x output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator x event according to EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator x event did not occur

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$
When CPOL = 1 (inverted polarity):
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt is generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.
01 = Trigger/event/interrupt is generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.
00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

REGISTER 20-4: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted ('0') comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted ('1') comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Inverted Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Inverted Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** Negative AND Gate Output Select
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** Positive AND Gate Output Select
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate A1 C Input Inverted Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate A1 C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

23.2 On-Chip Voltage Regulator

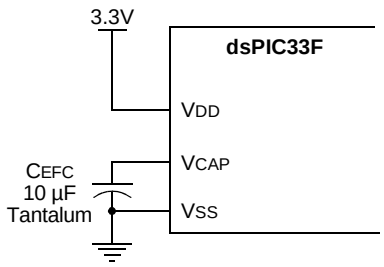
All of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 23-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 26-14 located in **Section 26.1 "DC Characteristics"**.

Note:	It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 23-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 26-14 located in **Section 26.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

23.3 BOR: Brown-out Reset

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an Oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 26-35: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

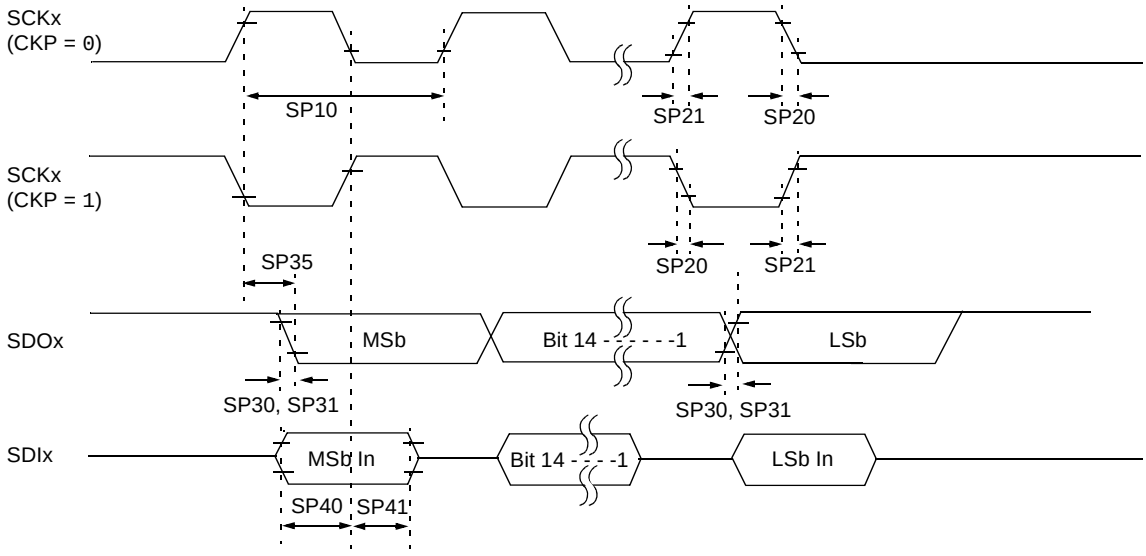
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-22: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-40: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	9	MHz	-40°C to +125°C, see **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 26-45: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

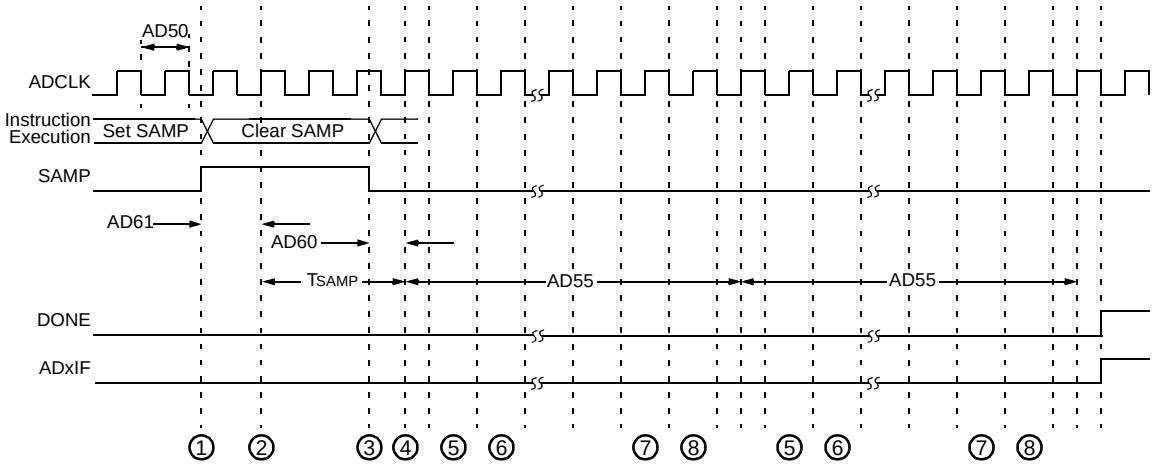
AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	See **Note 3**

Note 1: BRG is the value of the I2C™ Baud Rate Generator. Refer to **"Inter-Integrated Circuit (I2C™)"** (DS70195) in the "*dsPIC33/PIC24 Family Reference Manual*". Please see the Microchip web site for the latest "*dsPIC33/PIC24 Family Reference Manual*" sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

FIGURE 26-31: ADC CONVERSION TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



1 – Software sets ADxCON. SAMP to start sampling.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70183) in the "*dsPIC33/PIC24 Family Reference Manual*".

3 – Software clears ADxCON. SAMP to start conversion.

4 – Sampling ends, conversion sequence starts.

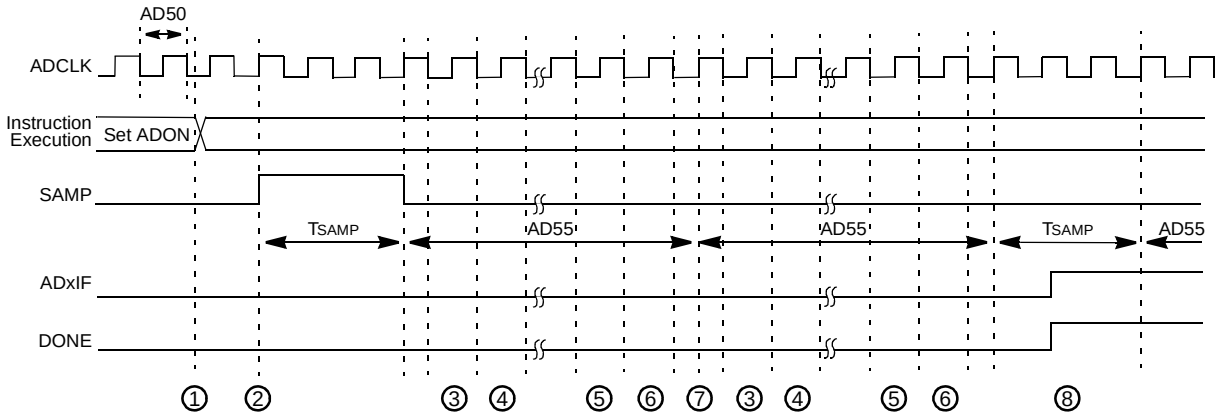
5 – Convert bit 9.

6 – Convert bit 8.

7 – Convert bit 0.

8 – One TAD for end of conversion.

FIGURE 26-32: ADC CONVERSION TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



1 – Software sets ADxCON. ADON to start AD operation.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33/PIC24 Family Reference Manual"*.

3 – Convert bit 9.

4 – Convert bit 8.

5 – Convert bit 0.

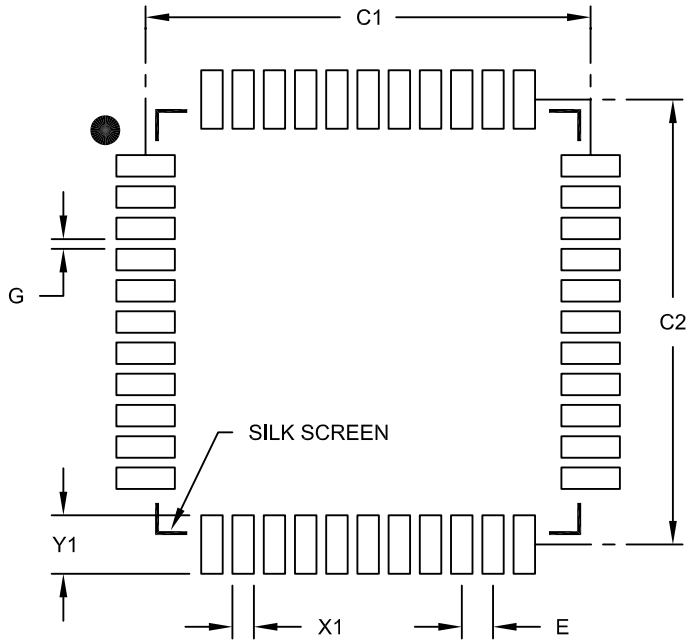
6 – One TAD for end of conversion.

7 – Begin conversion of next channel.

8 – Sample for time specified by SAMC<4:0>.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

APPENDIX A: REVISION HISTORY

Revision A (January 2011)

This is the initial released version of the document.

Revision B (February 2011)

All major changes are referenced by their respective section in Table A-1.

In addition, minor text and formatting changes were incorporated throughout the document.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, Ultra Low Cost 16-bit Digital Signal Controllers	Pin diagram updates (see **"Pin Diagrams"**): • 20-pin PDIP/SOIC/SSOP (dsPIC33FJ16MC101): Removed the $\overline{\text{FLTB1}}$ pin from pin 10 • 28-pin SPDIP/SOIC/SSOP (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTB1}}$ pin from pin 12 to pin 14; relocated the $\overline{\text{FLTA1}}$ pin from pin 16 to pin 15 • 28-pin QFN (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTA1}}$ pin from pin 13 to pin 12; relocated the $\overline{\text{FLTB1}}$ pin from pin 9 to pin 11 • 36-pin TLA (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTA1}}$ pin from pin 17 to pin 16; relocated the $\overline{\text{FLTB1}}$ pin from pin 10 to pin 15
Section 1.0 "Device Overview"	Added Notes 1, 2, and 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the Pinout I/O Descriptions (see Table 1-1). Added **Section ""**.
Section 4.0 "Memory Organization"	Updated All Resets value for PxFLTACON and PxFLTABCON to the 6-Output PWM1 Register Map (see Table 4-9). Added Note 1 to the PMD Register Map (see Table 4-29).
Section 6.0 "Resets"	Removed Reset timing sequence information from **Section 6.2 "System Reset"**, as this information is provided in Figure 6-2.
Section 15.0 "Motor Control PWM Module"	Added Note 2 and Note 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the 6-channel PWM Module Block Diagram (see Figure 15-1). Added **Section 15.2 "PWM Faults"** and **Section 15.3 "Write-protected Registers"**. Added Note 2 and Note 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the note boxes located below the PxFLTACON and PxFLTBCON registers (see Register 15-9 and Register 15-10).
Section 17.0 "Inter-Integrated Circuit™ (I^2C™)"	Updated the descriptions for the conditional If STREN = 1 and If STREN = 0 statements for the SCLREL bit in the I2Cx Control Register (see Register 17-1).
Section 23.0 "Special Features"	Added the RTSP Effect column to the dsPIC33F Configuration Bits Description (see Table 23-3).
Section 26.0 "Electrical Characteristics"	Added Parameters 300 and D305 (see Table 26-42 and Table 26-43).
Section 27.0 "Packaging Information"	Modified the pending TLA packaging page.

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